TEMSCON GLOBAL

MONTRÉAL, CANADA | AUGUST 4-7, 2026

Engineering Management, Innovation, and Leadership in a Time of Technological Disruption

CALL FOR PAPERS

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See the conference website for the full **Operating Committee**.

DEADLINES

INVITED SESSION PROPOSALS
January 31, 2026

SHORT & FULL PAPER SUBMISSIONS
March 15, 2026

WORKSHOP PROPOSALS
April 1, 2026

NOTIFICATION OF ACCEPTANCE
April 15, 2026

FINAL PAPER SUBMISSIONS
June 1, 2026

VENUE

ÉCOLE DE TECHNOLOGIE SUPÉRIEURE

Today’s world has been profoundly shaped by technological innovation. The scale and impact of technology on tomorrow’s world will be even greater, with attendant opportunities as well as predicaments arising from disruptive developments in areas such as artificial intelligence, quantum computing, and blockchain. From addressing societal challenges to meeting industry needs to facilitating entrepreneurial ventures, addressing imperatives of today and tomorrow will crucially rely on technology management and leadership.

TEMSCON Global is the flagship conference of the IEEE Technology and Engineering Management Society (TEMS) and is a premier venue for research on management, innovation, and leadership across the spectrum of technology, science, and engineering. The conference will convene researchers, managers, practitioners, educators, students, and policy makers to present and discuss new developments in the fields of interest of IEEE TEMS. The conference program will include contributions to this call for papers as well as plenary lectures, entrepreneurship sessions, and industry forums.

SUBMISSIONS FOR THE TEMSCON GLOBAL PROGRAM

TEMSCON Global welcomes submissions of full papers and short papers. Manuscripts that are accepted and presented will be submitted for inclusion in the IEEE *Xplore*® digital library and indexed by EI/Compendex. Authors of selected papers will be invited to submit extended versions for potential publication in special issues of *IEEE Transactions on Engineering Management* and *IEEE Engineering Management Review*. Proposals for workshops and invited sessions are also welcome. Refer to the conference website for further details and submission instructions.

TOPICS OF INTEREST *(PARTIAL LIST)*

MANAGEMENT OF TECHNOLOGIES

- Agentic and generative AI
- Machine learning and data analytics
- Edge and cloud computing
- Blockchain and distributed ledgers
- Cybersecurity and quantum

TECHNOLOGY AND BUSINESS STRATEGY

- Management of engineering organizations
- Innovation and entrepreneurship
- R&D and NPD management
- Supply chain and operations
- Digital transformation

SOCIETAL AND INDUSTRY APPLICATIONS

- Aerospace and defense
- Software and services
- Sustainability and climate change
- Smart cities and infrastructure
- Smart manufacturing and logistics

GOVERNANCE AND POLICY

- Science and technology policy
- Regulation and compliance
- Ethics of artificial intelligence
- National industrial policy
- Technology transfer

IEEE

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Montréal
Business events

IEEE-TEMSCON-GLOBAL.ORG/2026